

## ULTRAFAST SOFT RECOVERY RECTIFIER DIODE

### PRODUCT APPLICATIONS

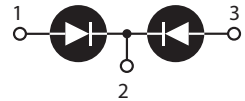
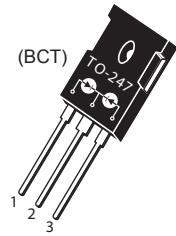
- Anti-Parallel Diode
  - Switchmode Power Supply
  - Inverters
- Free Wheeling Diode
  - Motor Controllers
  - Converters
  - Inverters
- Snubber Diode
- PFC

### PRODUCT FEATURES

- Ultrafast Recovery Times
- Soft Recovery Characteristics
- Popular TO-247 Package
- Low Forward Voltage
- Low Leakage Current
- Avalanche Energy Rated

### PRODUCT BENEFITS

- Low Losses
- Low Noise Switching
- Cooler Operation
- Higher Reliability Systems
- Increased System Power Density



- 1 - Anode 1  
 2 - Common Cathode  
 Back of Case - Cathode  
 3 - Anode 2

### MAXIMUM RATINGS

 All Ratings per leg:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT30DQ120BCT(G)	UNIT
$V_R$	Maximum D.C. Reverse Voltage		
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage	1200	Volts
$V_{RWM}$	Maximum Working Peak Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current ( $T_C = 103^\circ\text{C}$ , Duty Cycle = 0.5)	30	
$I_{F(RMS)}$	RMS Forward Current (Square wave, 50% duty)	43	Amps
$I_{FSM}$	Non-Repetitive Forward Surge Current ( $T_J = 45^\circ\text{C}$ , 8.3ms)	210	
$E_{AVL}$	Avalanche Energy (1A, 40mH)	20	mJ
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to 175	°C
$T_L$	Lead Temperature for 10 Sec.	300	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT	
$V_F$	Forward Voltage		$I_F = 30\text{A}$	2.8	3.3	Volts
			$I_F = 60\text{A}$	3.4		
			$I_F = 30\text{A}, T_J = 125^\circ\text{C}$	2.1		
$I_{RM}$	Maximum Reverse Leakage Current		$V_R = 1200\text{V}$		100	$\mu\text{A}$
			$V_R = 1200\text{V}, T_J = 125^\circ\text{C}$		500	
$C_T$	Junction Capacitance, $V_R = 200\text{V}$		36		pF	

## DYNAMIC CHARACTERISTICS

APT30DQ120BCT(G)

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$t_{rr}$	Reverse Recovery Time	$I_F = 1A, di_F/dt = -100A/\mu s, V_R = 30V, T_J = 25^\circ C$	-	26		ns
$t_{rr}$	Reverse Recovery Time	$I_F = 30A, di_F/dt = -200A/\mu s, V_R = 800V, T_C = 25^\circ C$	-	320		
$Q_{rr}$	Reverse Recovery Charge		-	545		nC
$I_{RRM}$	Maximum Reverse Recovery Current		-	4	-	Amps
$t_{rr}$	Reverse Recovery Time	$I_F = 30A, di_F/dt = -200A/\mu s, V_R = 800V, T_C = 125^\circ C$	-	435		ns
$Q_{rr}$	Reverse Recovery Charge		-	2100		nC
$I_{RRM}$	Maximum Reverse Recovery Current		-	9	-	Amps
$t_{rr}$	Reverse Recovery Time	$I_F = 30A, di_F/dt = -1000A/\mu s, V_R = 800V, T_C = 125^\circ C$	-	180		ns
$Q_{rr}$	Reverse Recovery Charge		-	2975		nC
$I_{RRM}$	Maximum Reverse Recovery Current		-	28		Amps

## THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			.80	$^\circ C/W$
$W_T$	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb•in
				1.1	N•m

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

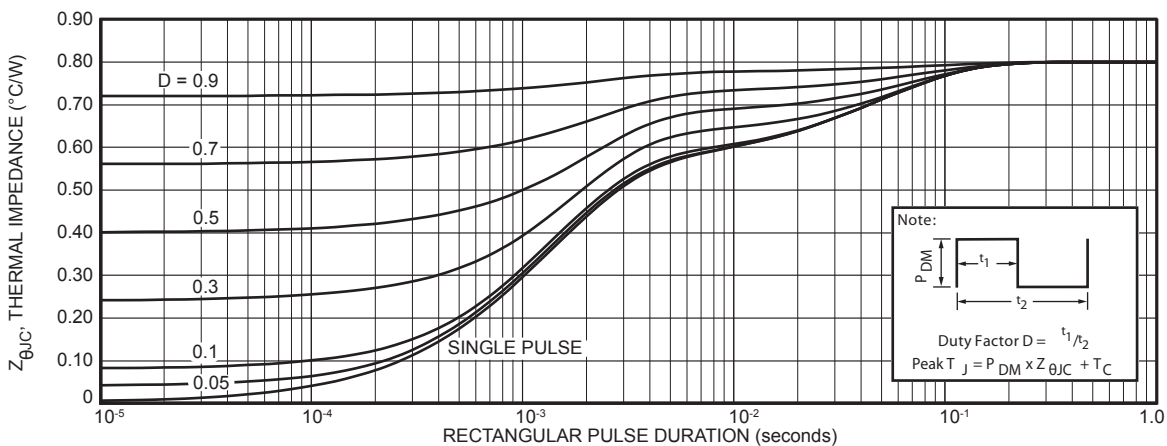


FIGURE 1. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

# TYPICAL PERFORMANCE CURVES

APT30DQ120B\_S(G)

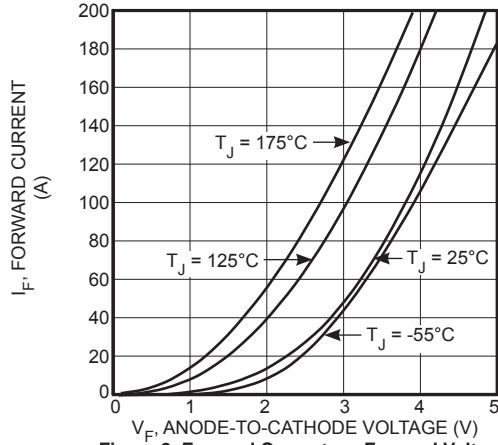


Figure 2. Forward Current vs. Forward Voltage

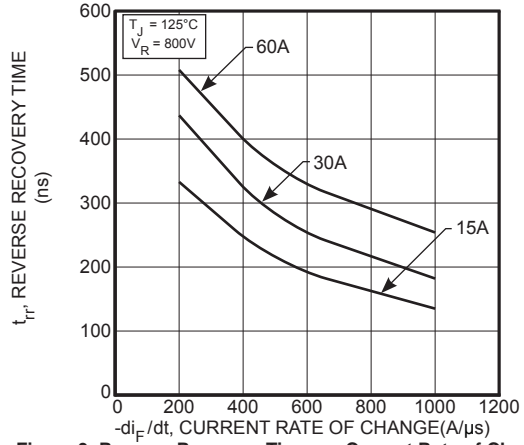


Figure 3. Reverse Recovery Time vs. Current Rate of Change

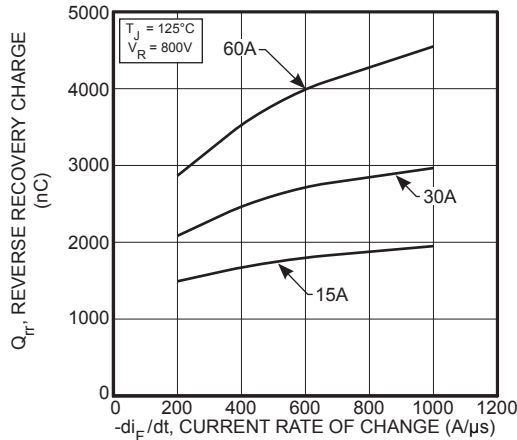


Figure 4. Reverse Recovery Charge vs. Current Rate of Change

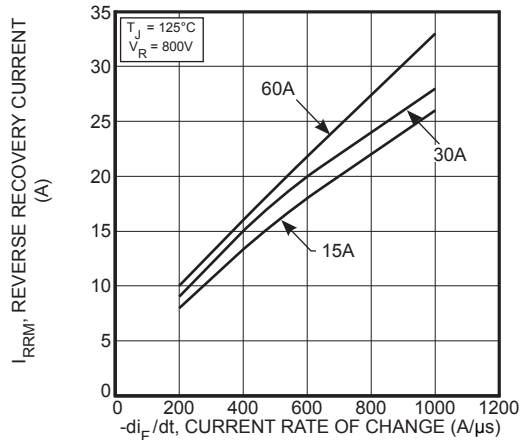


Figure 5. Reverse Recovery Current vs. Current Rate of Change

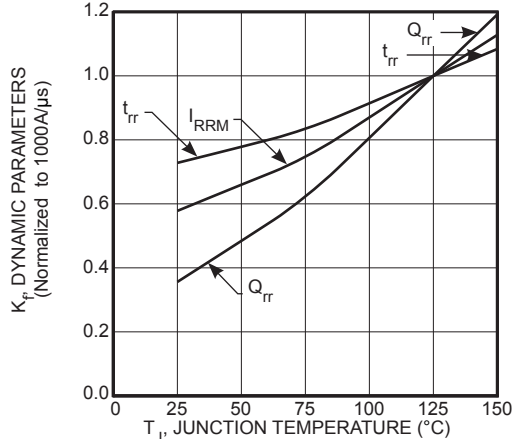


Figure 6. Dynamic Parameters vs. Junction Temperature

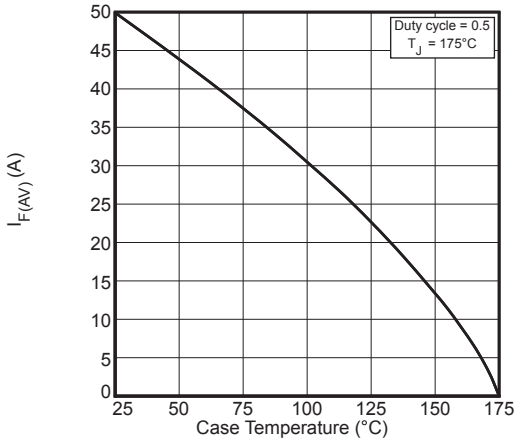


Figure 7. Maximum Average Forward Current vs. Case Temperature

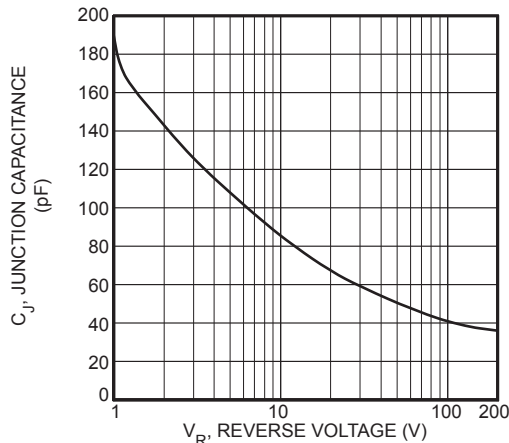


Figure 8. Junction Capacitance vs. Reverse Voltage

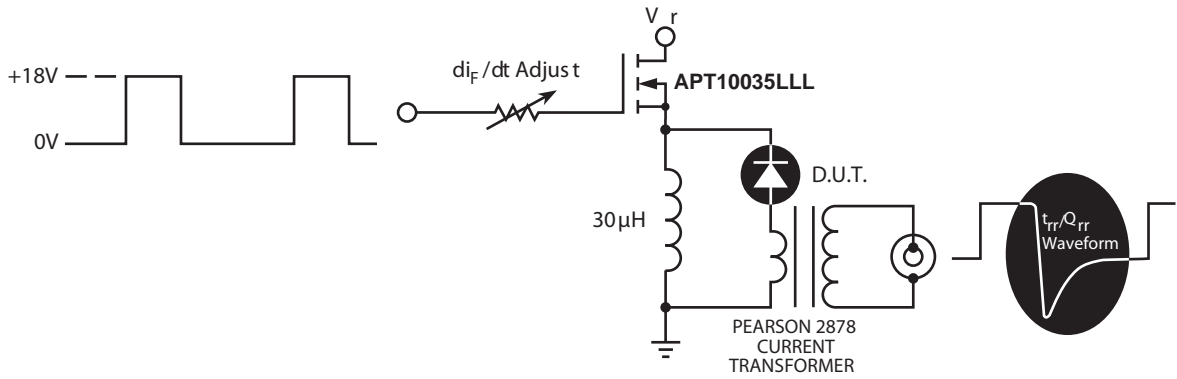


Fig. 9. Diode Test Circuit

- 1  $I_F$  - Forward Conduction Current
- 2  $di_F/dt$  - Rate of Diode Current Change Through Zero Crossing.
- 3  $I_{RRM}$  - Maximum Reverse Recovery Current
- 4  $t_{rr}$  - Reverse Recovery Time, measured from zero crossing where the diode current goes from positive to negative, to the point at which the straight line through  $I_{RRM}$  and  $0.25 I_{RRM}$  passes through zero.
- 5  $Q_{rr}$  - Area Under the Curve Defined by  $I_{RRM}$  and  $t_{rr}$ .

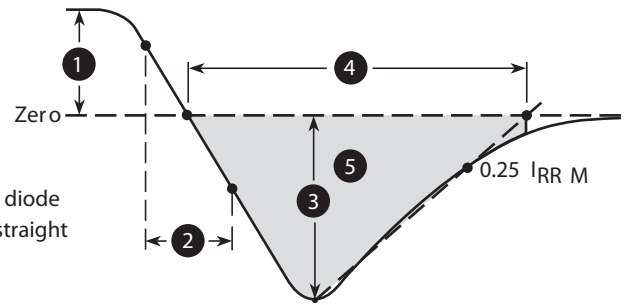
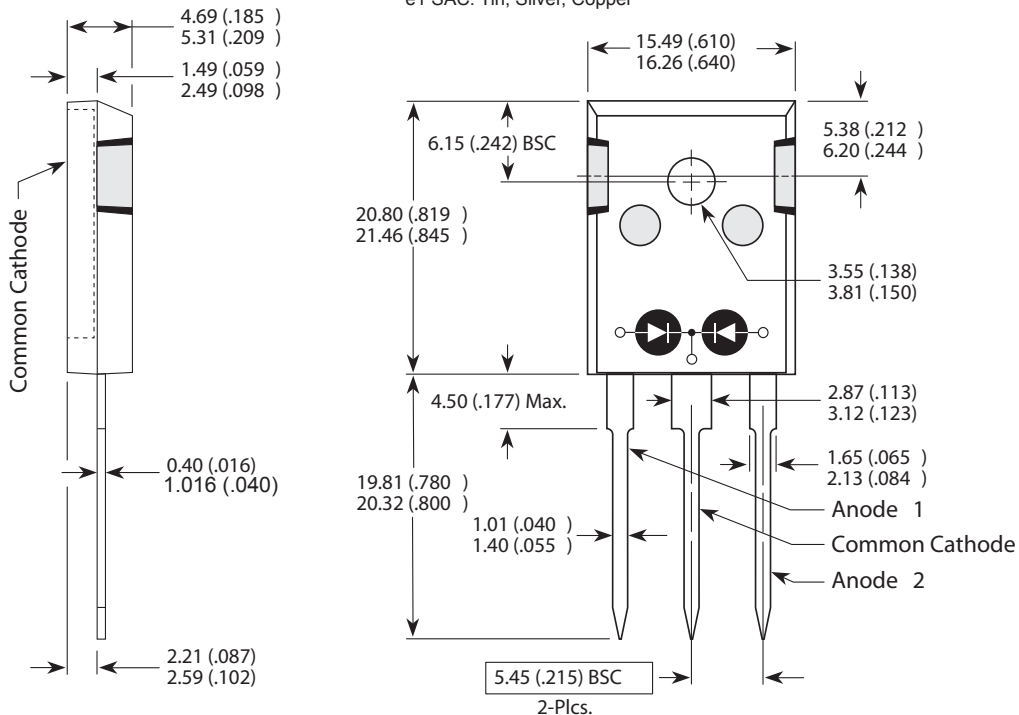


Fig. 10. Diode Reverse Recovery Waveform and Definition

### TO-247 Package Outline

e1 SAC: Tin, Silver, Copper



Dimensions in Millimeters and (Inches)

# Mouser Electronics

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[APT30DQ120BCTG](#)